TEXAS INSTRUMENTS

Bill of Materials

TI DESIGNS

TIDA-00306

Item	Qty	Fitted	Value	Part Description	PCB Footprint	Note
1	27		11,	CAP, SMD, Ceramic, 0603 20%	SMD0603-A-1	
2	1		C3	10uF - 7343 SMD, Tan, 20% 25V	SMD07343	
3	4		C28,C29,C30,C31	33U-7343 SMD, Tan, 20% 25V	SMD07343	
4	2		C33,C35	33PF CAP, SMD, Ceramic, 0805 10% 50V	SMD0805-A-1	
5	1		C40	33uF , Tantalum +/- 10% 16V 3528	SMD3528-B-1	
6	1		C41	68uF , Tantalum +/- 10% 16V 3528	SMD3528-B-1	
7	2		C87,C88	1500pF CAP, SMD, Ceramic, 1808 10% 2KV	SMD1808-A-1	
8	1		C91	10uF CAP, SMD, Tant, 3528 10% 16V	SMD3528-B-1	
9	4		C105,C106,C109,C110	0.001uF CAP, SMD, Ceramic, 0603 20% 16V	SMD0603-A-1	
10	3		C111,C112,C113	100nF CAP, SMD, Ceramic, 0603 20% 16V	SMD0603-A1	
11	1		C114	10uF , Tantalum +/- 10% 16V 3528	SMD3528-B-1	

Item	Qty	Fitted	Value	Part Description	PCB Footprint	Note
12	6		D2,D3,D4,D5,D6,D7	Bicolor-LEDs 7011X5/7	Digikey L61057CT_ND	
13	2		D9,D8	Ultra Bright Red Panasonic LNJ211R82RA		
14	1		D10	LTM673 OSRAM LTM673 Hyper-Bright LED	OSRAM/LTM673-R1S2-35	
15	1		J1	HDR-3X3	HDR-3X3	
16	1		J2	CON2x5_TH	cn-hdr2x5	
17	17		J4,J23,J36,J37,J40,J41, J48,J49,J50,J51,J52,J55, J56,J57,J58,J90,J92	HDR-1X2	CN-HDR1X2	
18	2	DNP	J13,J7	HDR-2X20	CN-MII-40P-RA-M	
19	2		J8,J10	HDR-1X3	CN-HDR1X3	
20	2	DNP	J9,J14	CON-MII-MALE	CN-MII-40P-RA-M	
21	1		J26	HDR2X2	CN-HDR2X2	
22	6		47	HDR_1X3	CN-HDR1X3	
23	1		J85	CON-RJ45	PHONE8P8C-	
24	1	DNP	J84	CON-RJ45	PHONE8P8C-	
25	1		J89	HFBR-5803	Connector	
26	1		J91	POE Connector	PPPC071LGBN	
27	1		J93	HDR2X5	CN-HDR2X5	
28	2		L1,L2	1uH Murata LQM21N Series	10D Ferrite	
29	1		R1	1.5K , SMD, 0805 1/10W 1%	RES	
30	1		R20	1%	SMD0603-A-1	
31	10		7,R50,	33 RES, SMD, 0603 1/16W 5%	SMD0603-A-1	
32	7	DNP	110,R112,R128	RES, SMD, 0603 1/16W 5%	SMD0603-A-1	
33	1		R63	5%	SMD0603-A-1	
34	25		4,R95,	2.2K RES, SMD, 0603 1/16W 5%	SMD0603-A-1	
35	13		107,	165 , RES, SMD, 0603 1/16W 1%	SMD0603-A-1	

Item	Qty	Fitted	Value	Part Description	PCB Footprint	Note
36	8		8,R143,	RES, 49.9 , SMD, 0603 1/16W 1%	SMD0603-A-1	
37	8		0,R161,	75 RES, SMD, 0603 1/16W 1%	SMD0603-A-1	
38	2		R166,R165	50 RES, SMD, 0603 1/16W 1%	SMD0603-A-1	
39	5		2,R217	130 RES, SMD, 0603 1/16W 1%	SMD0603-A-1	
40	12	DNP	2,R185,	RES, SMD, 0603 1/16W 1%	SMD0603-A-1	
41	9		6,R177,	0 SRES, SMD, 0603 1/16W 1%	MD0603-A-1	
42	5		8,R218	80 RES, SMD, 0603 1/16W 1%	SMD0603-A-1	
43	2		R223,R224	22 RES, SMD, 0603 1/16W 5%	SMD0603-A-1	
44	1		R225	10 RES, SMD, 0603 1/16W 5%	SMD0603-A-1	
45	1		R231	100 RES, SMD, 0603 1/16W 5%	SMD0603-A1	
46	1		R232	1200 RES, SMD, 0603 1/16W 5%	SMD0603-A1	
47	1		R233	33 RES, SMD, 0603 1/16W 5%	SMD0603-A1	
48	2		R234,R235	210 RES, SMD, 0603 1/16W 5%	SMD0603-A-1	
49	1	DNP	T2	Pulse/H1102/H2019	H1102/H2019	
50	1	DNP	T1	Pulse/H1102/H2019	H1102/H2019	
51	1		U1	Temperature Ethernet PHY with	VHB80A	
52	1		U3	Regulator 5V-3.3V	SOT223-5	
53	3		U4,U5,U6	STATE output	SOT23-5	
54	1	DNP	X1	50 MHz Oscillator (50 ppm), 3.3V	4P	
55	1		Y1	XTAL - Crystal, 25.000M	25M HC49-US	
56	14		MII_5V	Jumper 2Pos , 2.54mm Pitch	Jumper setting	

MII with Copper Configuration - Do Not Stuff Components
X1
R223, R224, R225,
J90
R174, R175, R178, R179, R239
J89

Item	Qty	Fitted	Value	Part Description	PCB Footprint	Note

MII with Fiber Configuration - Do Not Stuff Components
X1
R223, R224, R225,
J90
R173, R176, R177, R180

RMII with Copper Configuration - Do Not Stuff Components
Y1
C33, C35
J90
R174, R175, R178, R179, R239
J89

RMII with Fiber Configuration - Do Not Stuff Components
Y1
C33, C35
J90
R173, R176, R177, R180

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265